

Claims

Claim 1 (Original): A chip for use in a voice communication device comprising:
a bone conduction sensing pattern disposed within the chip; and
a microphone sensing pattern disposed within the chip.

Claim 2 (Original): The chip of claim 1 further comprising an integrated circuit portion interconnected to the bone conduction sensing pattern and the microphone sensing pattern.

Claim 3 (Original): The chip of claim 1 wherein the bone conduction sensing pattern is positioned on a first end of the chip, the first end opposite a second end of the chip, the microphone sensing pattern positioned on the second end of the chip.

Claim 4 (Original): A chip for use in a voice communication device comprising:
a substrate;
a piezoelectric polymer overlaying the substrate;
the piezoelectric polymer having a first pattern and a second pattern, the first pattern being an accelerometer sensor pattern and the second pattern being a microphone sensor pattern.

Claim 5 (Original): The chip of claim 4 further comprising an electronic sensor portion overlaying the substrate.

Claim 6 (Original): The chip of claim 5 wherein the electronic sensor portion includes a signal conditioning circuit.

Claim 7 (Original): The chip of claim 4 wherein the piezoelectric polymer is divided into a first portion and a second portion at opposite ends of the chip, the accelerometer sensor pattern defined within the first portion and the microphone sensor pattern defined within the second portion.

Claim 8 (Original): A voice communication device comprising:
a chip having a microphone sensor and an accelerometer.